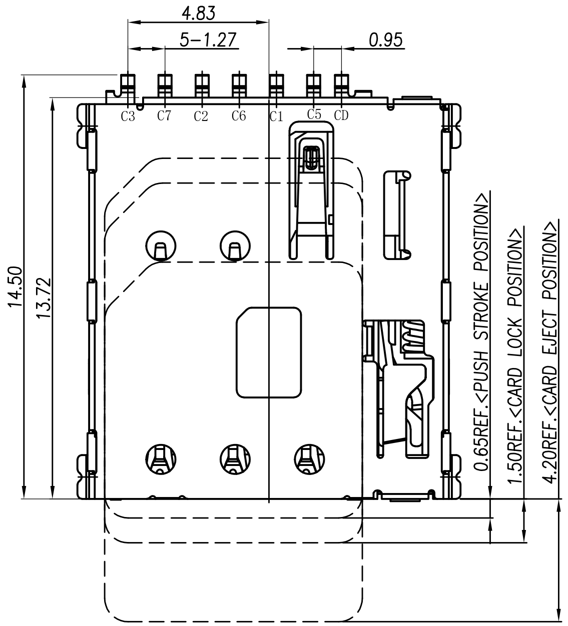
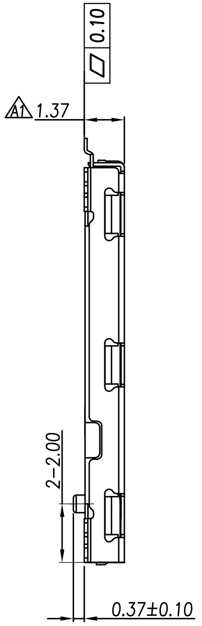
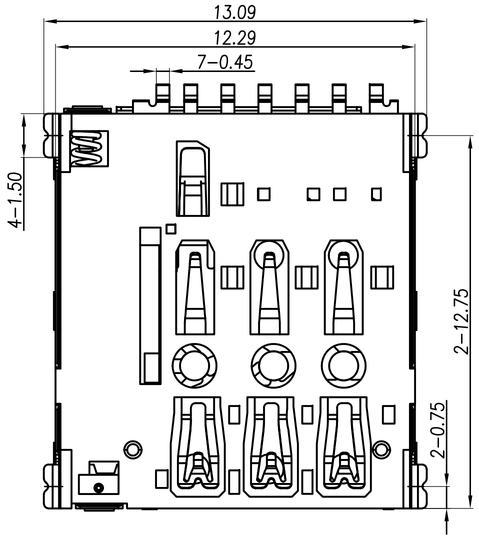
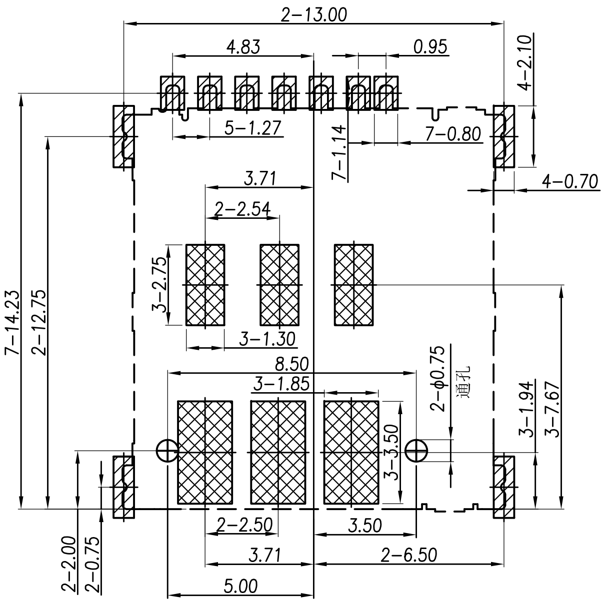
GP Component

REV.	ECN NO.	LOCATIONS	DESCRIPTION	DATE	DESIGN
A0			Initial	2020/06/12	Hanson
A1			Change DIM.	2022/03/02	Hanson









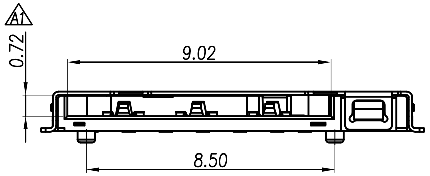
RECOMMENDED PCB LAYOUT

TOLERANCE:±0.05

▨ SMT SOLDER AREA

☒ COPPER RESTRICTED AREA

1. TOUCH AREA OF CONTACT TIPS NO ELECTRICAL FUNCTION
2. NO FIRST PCB_LAYOUT CIRCUITS IN THE AREA



MATRIX PART NO:

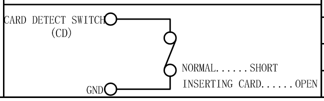
MSM − 01 − 01 − 07 − 14 − 80

- MSM: Matrix NANO SIM
- 01: 01: Push / 02: Non−Push
- 01: Plating 01: G/F / 30: 30u
- 07: Pin number 07: 7pin
- 14: Height
- 80: Series Number

NOTES:

1. MATERIAL:
   HOUSING: High Temperature Thermoplastic
   Terminal:Copper Alloy
   Shell: Stainless Steel
2. PLATING:
   Terminal:50u″ Ni UNDERPLATED OVERALL
   G/F PLATED ON CONTACT AREA AND SOLDER AREA
   Sheel:30u″ Ni UNDERPLATED OVERALL
   G/F PLATED ON CONTACT AREA AND SOLDER AREA
3. TECHNICAL SPECIALITY:
   RATED VOLTAGE: 30V AC MAX.
   CURRENT RATING: 0.5A MAX.
   INSULATION RESISTANCE:1000MΩ MIN
   CONTACT REISTANCE:100mΩ MAX
   WITHSTANDING VOLTAGE: 500V AC FOR 1 MINUTES
   OPERATING TEMPERATURE: −40℃~+85℃ Humidity 80% R.H MAX

CRICUIT DIAGRAM FOR CARD DETECT SWITCH



PIIN/NO	ASSIGNMENT
C1	VCC
C2	RST
C3	CLK
CD	Detect Switch
C5	GND
C6	VPP
C7	I/O

Matrix Electronics Co.,Ltd

TOLERANCE: X. X.X ±0.30 X.XX ±0.20 X.XXX ±0.10 ANGLE: ±3°	**DESIGN BY :** Hanson Huang	**DATE :** 2022/03/02	**PART NAME:** NANO−SIM PUSH/PUSH 1.37H	
	CHECKED BY: Vicky Hsieh	**DATE :** 2022/03/02	**PART NO.**	MSM−01−01−07−14−80
UNIT: mm [inch]	**APPROVED BY1:** Richard Hsieh	**DATE :** 2022/03/02	**MOLD NO.**	NA
SCALE:1:1 **SIZE:A4**	**APPROVED BY2:** Richard Hsieh	**DATE :** 2022/03/02	**DRAW NO.** **SHEET NO.**	 1 OF 1